AMP-IN

TE Internal #: 60789-8

TE Internal Description: .058 DIA RECEPTACLE LP 20-24 GPBECU

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Terminals & Splices > PCB Terminals











PCB Terminal Type: Receptacle

PCB Hole Diameter: 3.68 mm [.145 in]

Mating Pin Diameter: 1.47 mm [.058 in]

Compatible Insulation Diameter (Max): 1.78 mm [.07 in]

Compatible Insulation Diameter Range: 1.14 – 1.78 mm [.045 – .07 in]

Features

Product Type Features

Terminal Features

Wire Insulation Support Retention Type	Open Barrel
Contact Features	
Contact Underplating Material Thickness	1.27 μm[50 μin]
Contact Mating Area Plating Material Thickness	.38 μm[15 μin]
PCB Terminal Type	Receptacle
Mating Pin Diameter	1.47 mm[.058 in]
Terminal Plating Material	Gold
Contact Underplating Material	Nickel
Terminal Orientation	Straight

Stud Hole

Termination Features

Termination Method to PCB	Through Hole - Solder
Product Terminates To	Wire & Cable
Marahantan Attarlanaant	

Mechanical Attachment

Wire Insulation Support	With



Dimensions

Terminal Material Thickness	.25 mm[.01 in]
PCB Hole Diameter	3.68 mm[.145 in]
Compatible Insulation Diameter (Max)	1.78 mm[.07 in]
Compatible Insulation Diameter Range	1.14 – 1.78 mm[.045 – .07 in]
Wire Size	$.26 \text{ mm}^2$

Usage Conditions

Insulation Option	Uninsulated
Packaging Features	
Packaging Quantity	1000
Packaging Method	Bag

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2023 (233) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not applicable for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach



Customers Also Bought

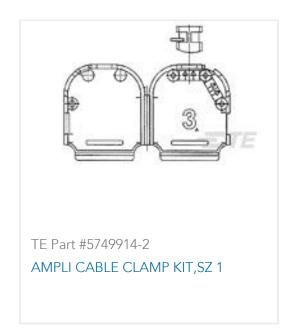














Documents

CAD Files

Customer View Model

ENG_CVM_60789-8_AE.3d_igs.zip

English

Customer View Model

ENG_CVM_60789-8_AE.3d_stp.zip

English

Customer View Model

ENG_CVM_60789-8_AE.2d_dxf.zip

English

3D PDF

English

3D PDF

3D

Customer View Model

ENG_CVM_60789-8_G.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_60789-8_G.3d_igs.zip

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Customer View Model

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English

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Datasheets & Catalog Pages

PRINTED CIRCUIT BOARD TERMINALS AND DISCONNECTS

English

Product Specifications

Application Specification

English